TECHNICAL DATA SHEET

CATEGORY: WATER SOLUBLE PASTE FLUX

NAME: WS483

FEATURES
- High Activity Level           - Good Thermal Transfer             - Will Not Foam During Wash
- Improved Environmental Resistance         - Excellent Wetting           - Extended Cleaning Window

DESCRIPTION
WS483 paste flux is an organically activated formulation composed of the same basic materials found in WS483 water soluble solder paste, ensuring its compatibility. WS483 paste flux may be utilized for ball attach, flip chip, die attach, tinning, rework and other standard paste flux applications. WS483 paste flux offers improved humidity resistance and open time, while maintaining high tack, in addition to an improved activity level and an enhanced wetting capability. WS483 paste flux also provides an exceptional post-process cleaning window and will not foam during the cleaning process, even in high pressure wash systems.

HANDLING
- This material has a shelf life of 6 months at 4 -12°C (39 - 54°F) and 3 months at 20 - 25°C (68 - 77°F).
- Do not store near fire or flame.
- Keep paste flux away from sunlight as it may degrade the product.

PASTE FLUX APPLICATION
- WS483 paste flux can be applied either directly from syringes via dispensing needles or from other packages via acid brush or other applicator.
- Apply directly onto components, PCBs, or wires.

CLEANING
WS483 can be cleaned easily with normal tap water. However, deionized water is recommended for the final rinse. A temperature of 100° - 150°F is sufficient for removing residues. An in-line or other pressurized spray cleaning system is suggested, but is not required.

PACKAGING
WS483 paste flux comes standard in syringes, jars, and cartridges.

SAFETY
- Use with adequate ventilation and proper personal protective equipment.
- Refer to the accompanying Material Safety Data Sheet for any specific emergency information.
- Do not dispose of any waste materials in non-approved containers.

IPC CLASSIFICATION

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<tr>
<td>J-STD-004</td>
<td>ORM0</td>
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